## Hacking the Packet in ASIC with an eFPGA

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## Achronix® Data Acceleration

# How to Achieve UDP-to-TCP loopback latency of under 10 ns with an eFPGA-enabled ASIC

Agenda:

- 1. SerDes support on next generation large package FPGAs
- 2. eFPGA overview and HFT benefits
- 3. Example HFT ultra-low-latency block diagram
- 4. Overview of the TSMC VCA program
- 5. Highlights of the Achronix eFPGA IP solution



#### Large Package, High-End FPGA Solutions Move to Support LR SerDes



Port speeds of 25 Gbps and above require forward error correction (FEC) to ensure interoperability

#### Forward Error Correction for 25G transceivers (IEEE 802.3by)



#### **EE Concerns for large-package, high-end FPGAs**

- SerDes drive strength and insertion loss:
  - Drive meaningful PCB trace lengths
  - Avoid FPGA routing congestion close to the package
  - Provide support for connectors and backplanes



### eFPGA Overview - Flexible Fabric Configuration and Sizing

- eFPGA resources are designed as building block structures that combine easily
- The customer defines an eFPGA resource mix to best meet their needs
- IP is delivered as a set of physically laid out transistors for efficient ASIC integration





#### Top Three Benefits of an eFPGA-enabled ASIC for HFT

1. Enables a programmable tick-to-trade solution with best-in-class latency

- 2. Maintain your current technology flow with FPGA updates
- 3. Define your own custom architecture to get the most out of your trading platform



- 100x lower FPGA-to-ASIC latency
- Direct die connectivity
- Custom interconnect



- 10x increase in bandwidth vs. standalone FPGA
- Direct die connectivity



### UDP-to-TCP Loopback Latency of Under 10 ns with a ULL Data Path



Not a STAC benchmark

Data Acceleration

#### Hardware-Proven, Ultra-Low-Latency PMA

DFE not normally used in low latency applications

## Low latency option



1000 5 UI from rising edge of TXWCLK# to first bit TXREFCLK CKP PLL & BG Control out of Serializer СКИ TXLOCK < Shared PLL / & Ser/Des width HSTCLK Common Block Bias can be made 8b, 22b, TX#N Analog delay < 1 UI to match FIFO... TXMODE[2:0] Serializer (1:8, 10, 16, Example with 10.3Gbps. TXWCLK# 20, 32, or 40) TX#P 8b word. Loop back Latency = 2.23 ns LPBO# Control, Beacon, OOB Tx: 5 + 1 UI = 0.58ns # = lane number Rx: 8 + 1 UI = 0.87ns RXREFCLK Channel: 8 UI = 0.78ns One CDR PLL/lane PLL & BG Control -8 UI from last bit TSMC 12/16FFC supports RXLOCK# received to rising edge to 16Gbps/lane; 25.8Gbps HSRCLK LPBI# in planning of RXWDCLK# (data RX#P RXMODE ------Deserializer DFE, ready) RXWCLK# (1:8, 10, 16, Eye Monitor, RXD#[39:0] - 40 20, 32, or 40) Presence RX#N Control, Status, Squelch Analog delay < 1 UI



Slide courtesy of Silicon Creations

### **TSMC Value Chain Aggregators**



- TSMC VCA program is well established and looking for new customers
  - Thousand of successfully completed SoC and ASIC developments
  - One-stop shop for ASIC design and manufacturing
  - Support for low-volume, multiproject wafers as well as full wafer production



#### **TSMC VCA Program**

#### Specification Architecture IP Software Physical Design Prototyping **Driver Development**, **Physical Design** Firmware, **RISC-V** Tool **Product Requirement** Architecture Analysis, IP Development, Chain **FPGA & Emulation** & Specification **RTL Design & Verification Selection & Integration Flexible Engineering Relationships** Fabrication Spec Handoff Chip RTL Handoff → Chip Netlist Chip GDS2 Handoff Chip Wafer Fabrication Silicon Bring Up Production Chips **Boards** Test Assembly **Board Design & Packaged ASIC Parts Test & Product** Package & **Production & Post Silicon Validation &** Manufacturing Assembly Logistics Engineering Software Bring-up

#### Achronix Speedcore<sup>™</sup> eFPGA Compiler: Fast Development of Customer-Specific Speedcore IP

#### **Deliverables** Inputs **IP Deliverables Resource Mix** LUT/register count GDSII of eFPGA IP core • . Memory configuration Simulation files • Memory density SI and PI models DSP density Test models Custom eFPGA tiles Timing . • Number of I/O Documentation Aspect ratio **Custom ACE Design Tool Suite** 100+ X10. ¥ ... **Technology Decisions** Instances Ports Pins Nets Paths Site Add Results to Selectio Ports ⇒Pies ≪Nets Foundry ٠ 3+Paths Selection II Technology node 2 3 1 0 9 4 4 k Domain Name Hi... Flops LUTs ALUs Nets Paths Voltage Process node Critical Paths 21 C ID Assignment Metal stack (X=229376, Y=17596416

Over 10 million Speedcore eFPGA IP cores have shipped in customer ASICs



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**Thank You** 

## Achronix is here to help you make your next eFPGA enabled ASIC a success!

<u>We look forward to meeting you.</u> Please come to the Achronix Semiconductor breakout sessions to learn more about our Speedcore eFPGA technology.

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